

# **Injection Molding Can Leave You Stressed And Warped. Moldflow Can Help**

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# Speaker Biography:

Zhiliang is a senior principal research engineer in the Autodesk simulation group. He has 30-year research and development experience in computer-aided engineering. After he obtained his Ph.D. in 1991, he worked in Tongji University(Shanghai), Tsinghua University(Beijing), University of Salford(Manchester) and Imperial College(London). Zhiliang joined Moldflow Pty. Ltd. in 1996. Since then, he has been a principal developer for Moldflow's shrinkage, warpage and stress products, and handled numerous real-world warpage simulation cases. Zhiliang has more than 35 published works—including journal papers, book chapters, and conference papers—and holds a patent.

# Description:

During this class we will address major issues related to 3D shrinkage and warpage analysis in injection molding. We would like to start with an introduction of mechanism of shrinkage and warpage. We will discuss the generic shrinkage model and its limitations. We will also present 3D thermo-viscous-elastic residual stress model and thermo-viscoelastic residual stress model. Finally, we will explore some advanced topics, such as corner-effect, in-mold shrinkage, stress relaxation, buckling, and large deflection analysis.

# Warpage: Related to nearly every part of Moldflow technologies

## Complexity:

Material data

Processing condition

Geometric modelling

Physical modelling

Mesh quality

Solidification criterion

Gate freezing time

Cooling rate effect

Crystallization

Pressure/temperature solution

Fiber orientation

Composite property

Shrinkage model

Structural solver

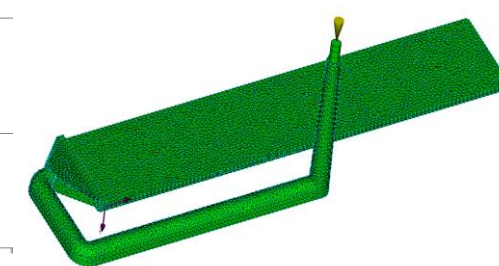
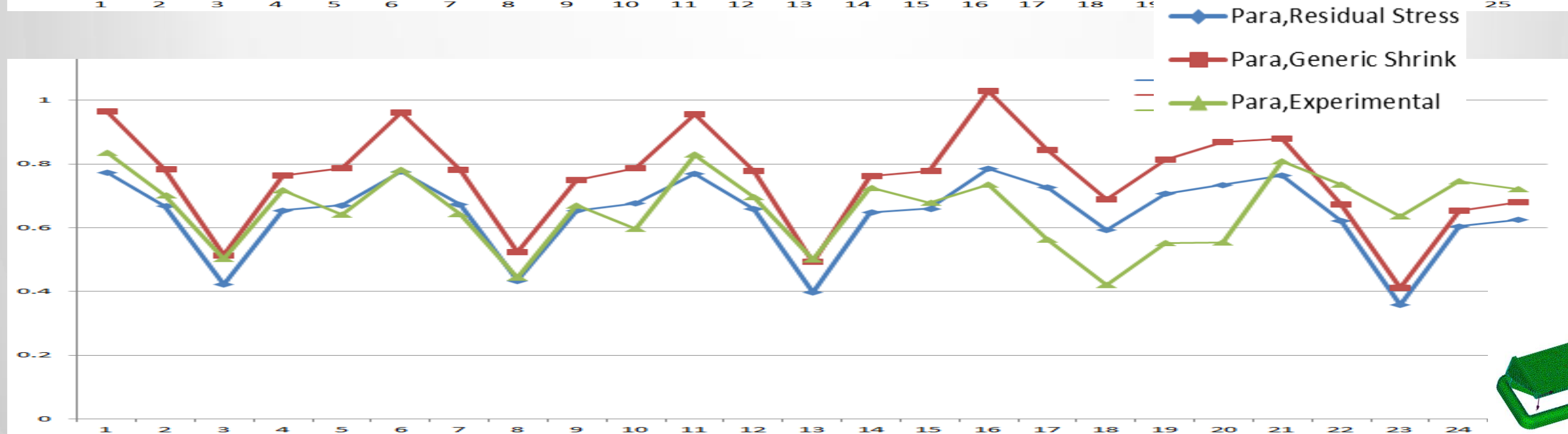
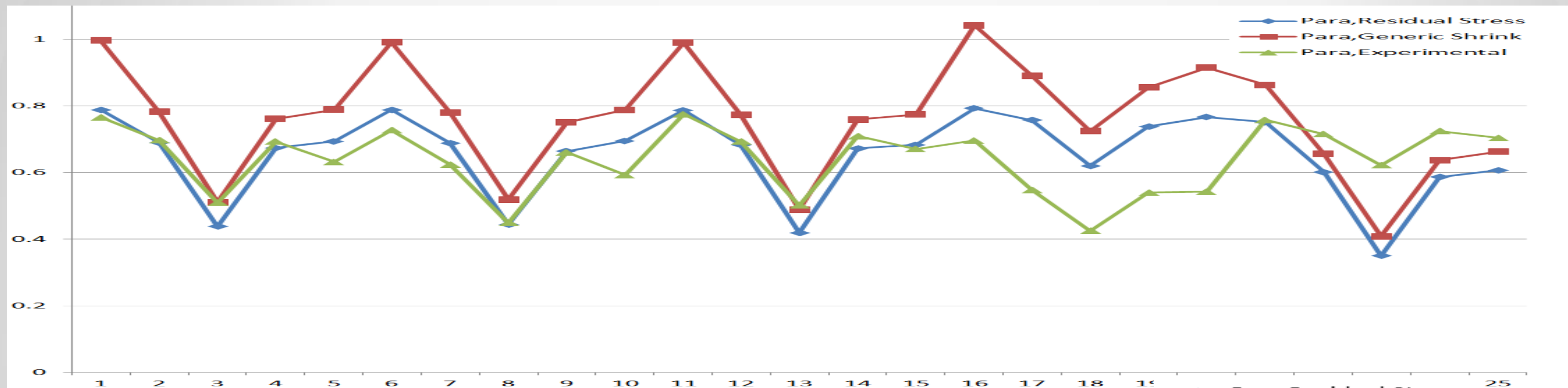
Mold deformation

Density relaxation

Validation

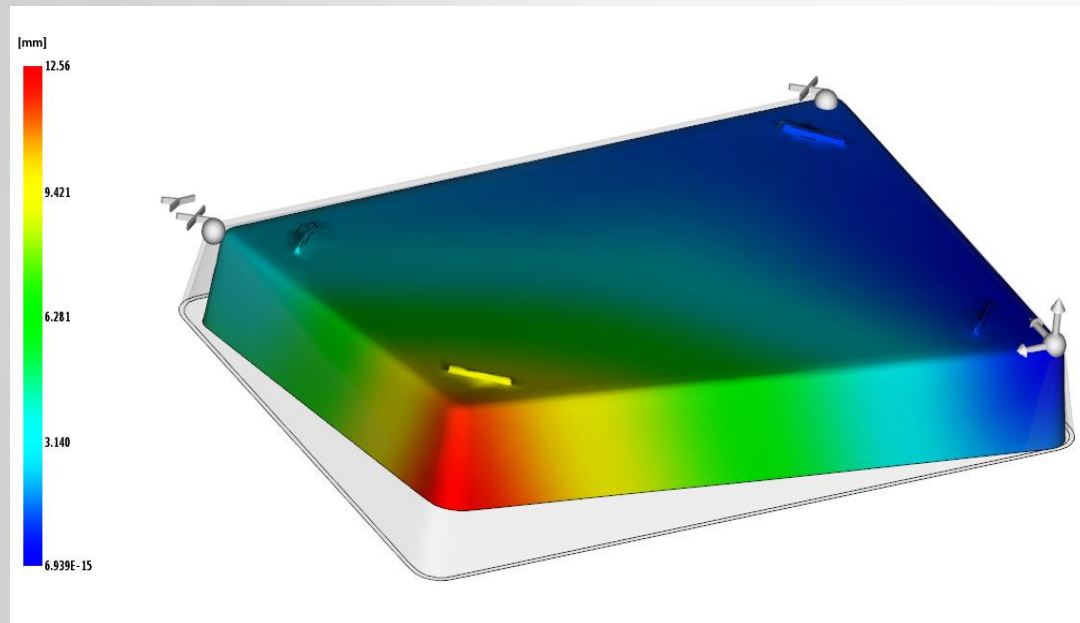
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# MF Tagdie Models: Unfilled materials

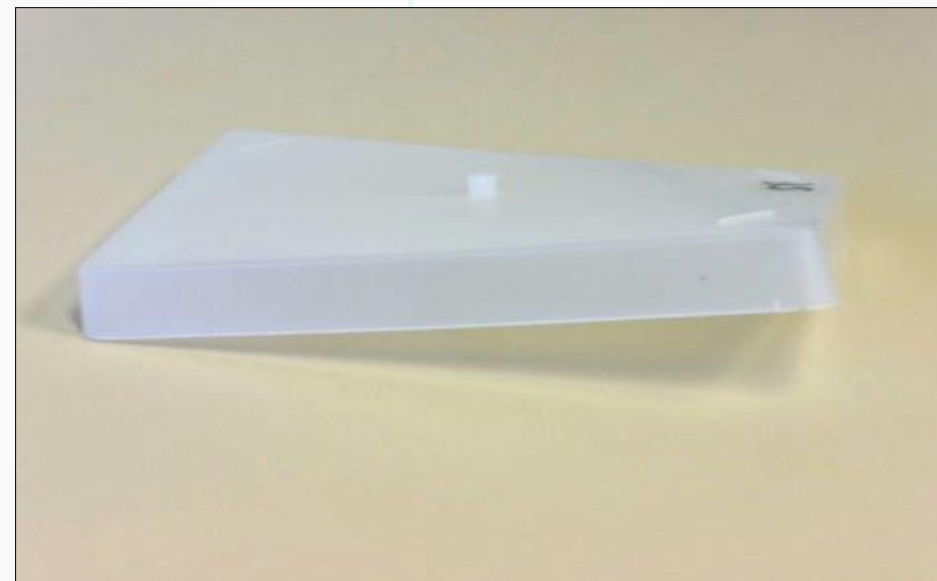


# MF Lab Tray

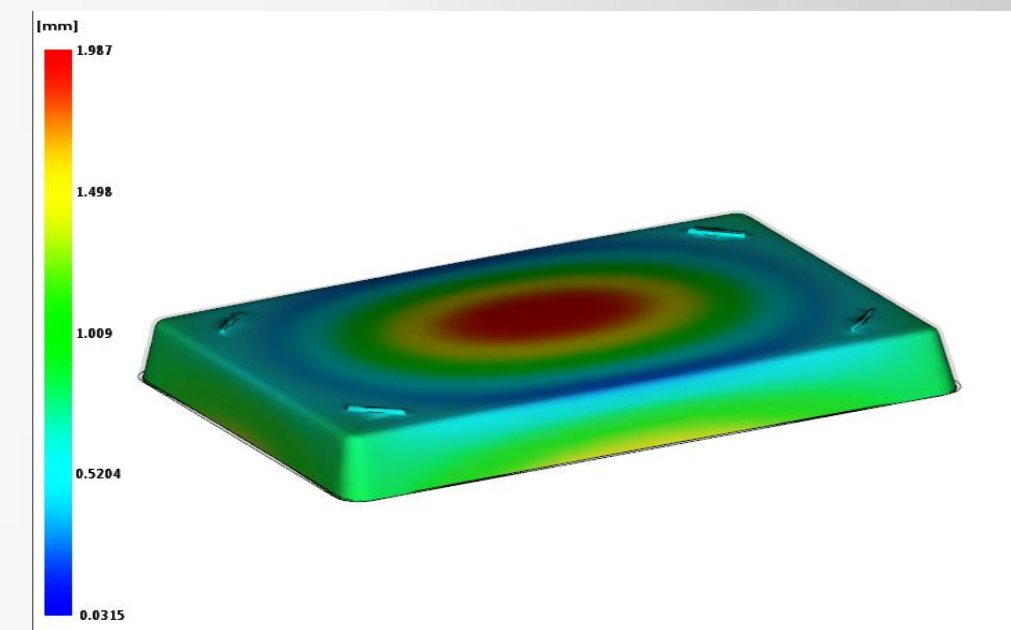
## Residual Stress Model



## Experimental Result



## Generic Shrinkage Model



# Conformal Cool Box:

PA6 30% GF - BASF Ultramid B3WG6 BK00564 [MAT5460]

